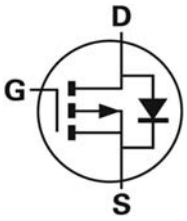
SGP3008E

-30V P-Channel Power MOSFET

	PDFN 3.3x3.3-8L	
V_{DSS} , -30V $R_{DS(ON)}$, 9.5mΩ (max.) @ V_{GS}=-10V $R_{DS(ON)}$, 15mΩ (max.) @ V_{GS}=-4.5V I_D , -39 A		

Description

The SGP3008E uses advanced Trench technology and designs to provide excellent $R_{DS(ON)}$ with low gate charge. This device is suitable for use in PWM, load switching and general purpose applications.

Features

- Low On-Resistance
- Low Input Capacitance
- Low Miller Charge
- Low Input / Output Leakage
- Pb-free lead plating; RoHS compliant

Applications

- Lithium-Ion Secondary Batteries
- Load Switch
- DC-DC converters and Off-line UPS

Ordering Information

Ordering Code	RoHS Status	Package	Package Code	Packing	Quantity
SGP3008E	Halogen-Free	PDFN 3.3x3.3-8L	E	Tape & Reel	5,000

Absolute Maximum Ratings (T_A=25°C unless otherwise noted)

Parameter		Symbol	Value	Unit
Drain-Source Voltage		V_{DS}	-30	V
Gate-Source Voltage		V_{GS}	±20	V
Drain Current-Continuous	T_C=25°C	I_D	-39	A
	T_C=100°C		-25	A
Drain Current-Pulsed Note 1		I_{DM}	-67	A
Avalanche Current, L=0.1mH		I_{AS}	-30	A
Avalanche Energy, L=0.1mH		E_{AS}	45	mJ
Maximum Power Dissipation	T_C=25°C	P_D	20.8	W
	T_C=100°C		8.3	W
Storage Temperature Range		T_{STG}	-55 to +150	°C
Operating Junction Temperature Range		T_J	-55 to +150	°C

Thermal Resistance Ratings

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
Thermal resistance, Junction-to-Ambient Note 2	$R_{\theta JA}$	Steady State	-	59.2	80	°C/W
Thermal resistance, Junction-to-Case Note 2	$R_{\theta JC}$	Steady State	-	6	8	°C/W

Electrical Characteristics (T_J=25°C unless otherwise noted)

OFF CHARACTERISTICS						
Parameter	**Symbol**	**Conditions**	**Min.**	**Typ.**	**Max.**	**Unit**
Drain-Source Breakdown Voltage	BV_{DSS}	V_{GS}=0V, I_{DS}=-250μA	-30	-	-	V
Zero Gate Voltage Drain Current	I_{DSS}	V_{DS}=-24V, V_{GS}=0V	-	-	-1	μA
Gate-Body Leakage	I_{GSS}	V_{GS}=±20V, V_{DS}=0V	-	-	±100	nA

ON CHARACTERISTICS						
Parameter	**Symbol**	**Conditions**	**Min.**	**Typ.**	**Max.**	**Unit**
Gate Threshold Voltage	$V_{GS(TH)}$	V_{DS}=V_{GS}, I_{DS}=-250μA	-1.0	-	-2.5	V
Drain-Source On-State Resistance	$R_{DS(ON)}$	V_{GS}=-10V, I_{DS}=-15A	-	-	9.5	mΩ
		V_{GS}=-4.5V, I_{DS}=-8A	-	-	15	mΩ

DYNAMIC CHARACTERISTICS						
Parameter	**Symbol**	**Conditions**	**Min.**	**Typ.**	**Max.**	**Unit**
Input Capacitance	C_{iss}	V_{DS}=-15V, V_{GS}=0V, f=1MHz	-	3875	-	pF
Output Capacitance	C_{oss}		-	398	-	
Reverse Transfer Capacitance	C_{rss}		-	278	-	
Gate Resistance	R_g	V_{GS}=0V, V_{DS}=0V, f=1MHz	-	2.89	-	Ω

SWITCHING CHARACTERISTICS						
Parameter	**Symbol**	**Conditions**	**Min.**	**Typ.**	**Max.**	**Unit**
Turn-On Delay Time	$T_{d(on)}$	V_{DD}=-15V, V_{GS}=-10V, R_G=3Ω, I_D=-20A	-	13.9	-	ns
Rise Time	t_r		-	64.1	-	
Turn-Off Delay Time	$T_{d(off)}$		-	51.8	-	
Fall Time	t_f		-	53.1	-	
Total Gate Charge	Q_g	V_{DS}=-15V, V_{GS}=-10V, I_D=-20A	-	63.5	-	nC
Gate to Source Gate Charge	Q_{gs}		-	14.7	-	
Gate to Drain “Miller” Charge	Q_{gd}		-	8.83	-	

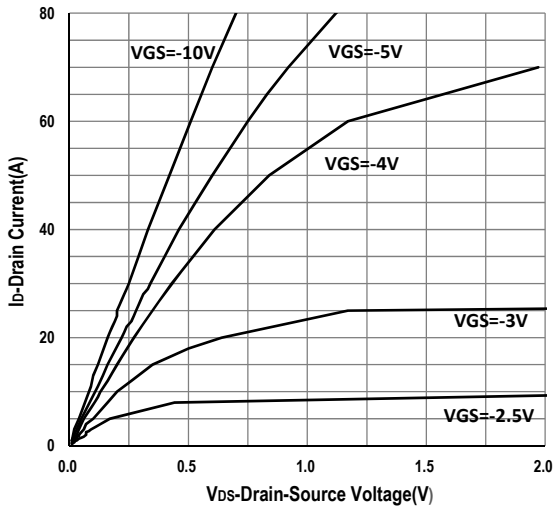
DRAIN-SOURCE DIODE CHARACTERISTICS AND MAXIMUM RATINGS						
Parameter	**Symbol**	**Conditions**	**Min.**	**Typ.**	**Max.**	**Unit**
Drain-Source Diode Forward Voltage	V_{SD}	V_{GS}=0V, I_S=-1A	-	-	-1.2	V
Body Diode Reverse Recovery Time	t_{rr}	V_{DD}=-24V, I_F=-20A, di/dt=100A/μs	-	23.0	-	ns
Body Diode Reverse Recovery Charge	Q_{rr}	V_{DD}=-24V, I_F=-20A, di/dt=100A/μs	-	16.0	-	nC
Reverse Recovery Current	IRRM	V_{DD}=-24V, I_F=-20A, di/dt=100A/μs		1.27		A

Notes:

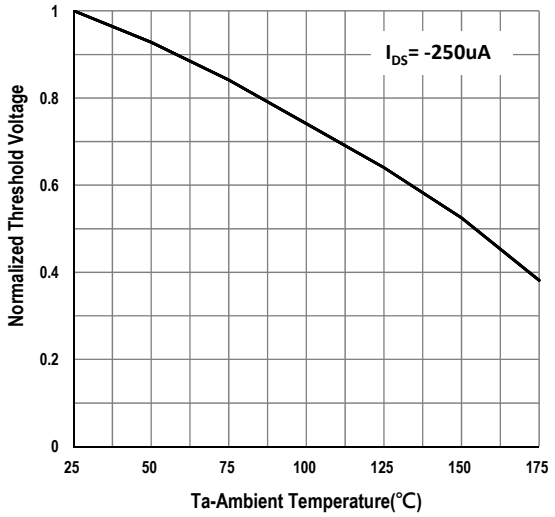
1. Pulse Test: Pulse Width ≤ 10ms, Duty Cycle ≤ 1%.
2. For surface-mounted devices, both $R_{\theta JA}$ and $R_{\theta JC}$ are measured with the device mounted on approximately 1”×1” FR-4 PCBs. In actual applications, many factors including the PCB material and layout, may affect the thermal resistance of the device-board assembly. For best results, characterize the thermal resistance directly in the application circuit.

Typical Operating Characteristics

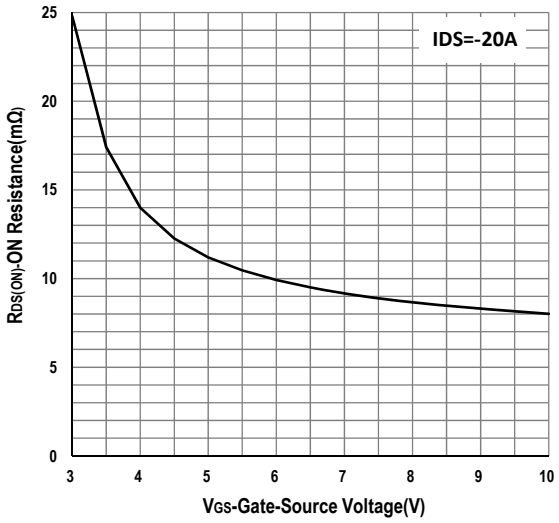
Output Characteristics



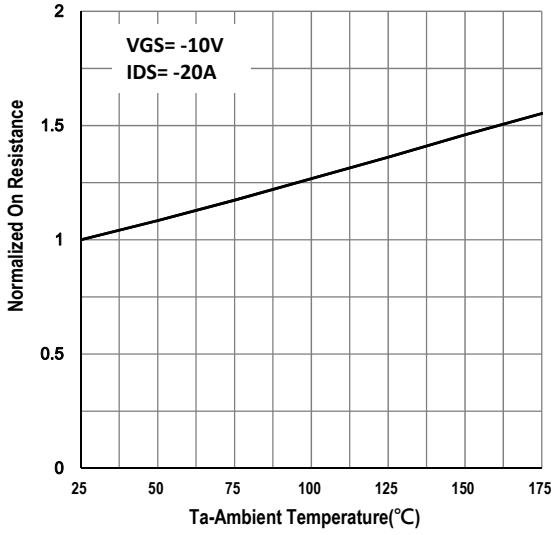
Gate Threshold Voltage



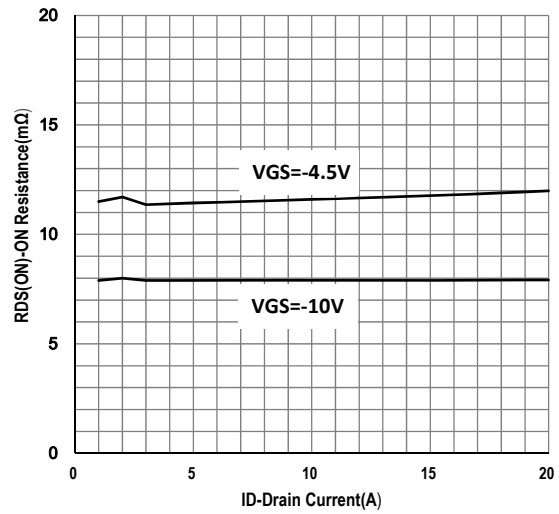
Gate-Source On Resistance



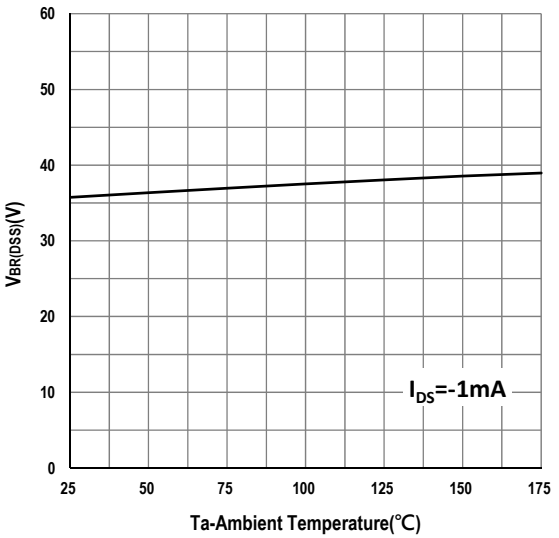
Drain-Source On Resistance



Drain-Source On Resistance

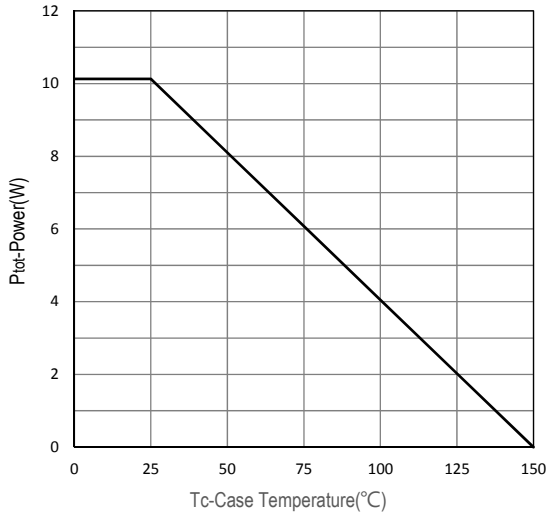


Source-Drain Diode Forward

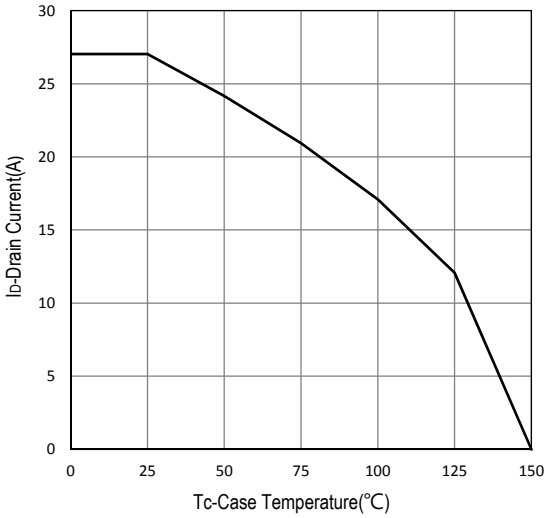


Typical Operating Characteristics (Cont.)

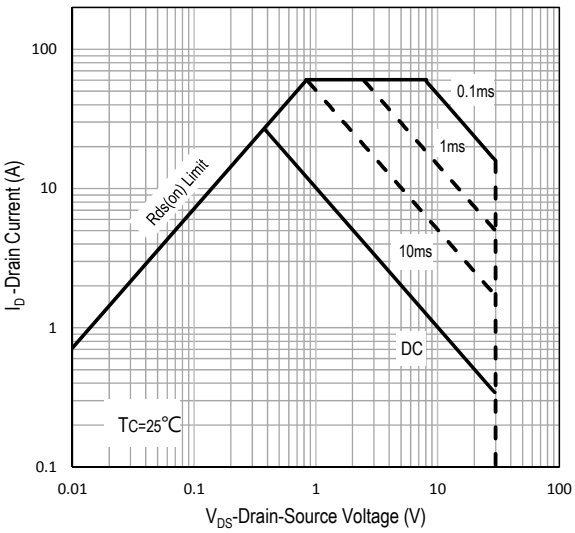
Power Dissipation



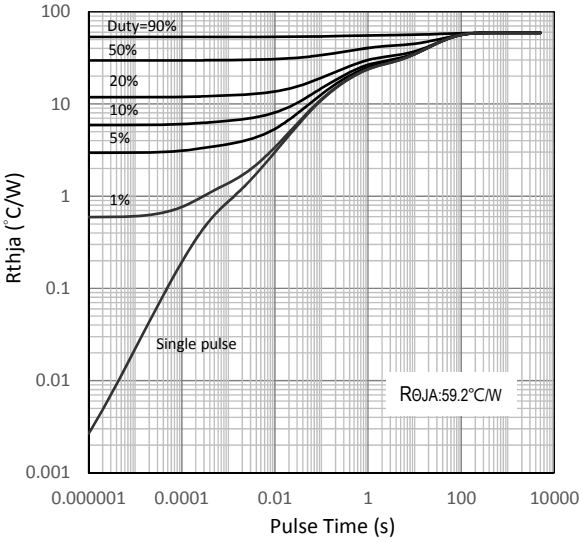
Drain Current



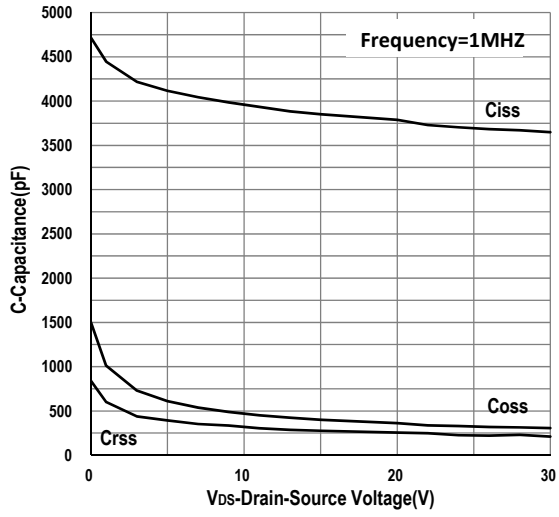
Safe Operation Area



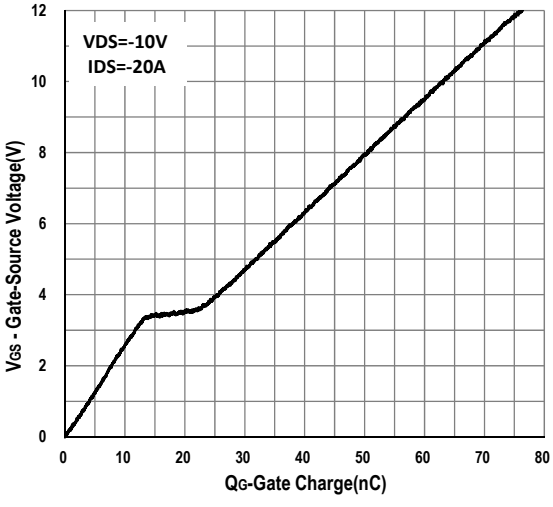
Transient Thermal Impedance



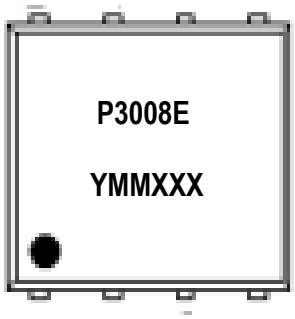
Capacitance



Gate Charge



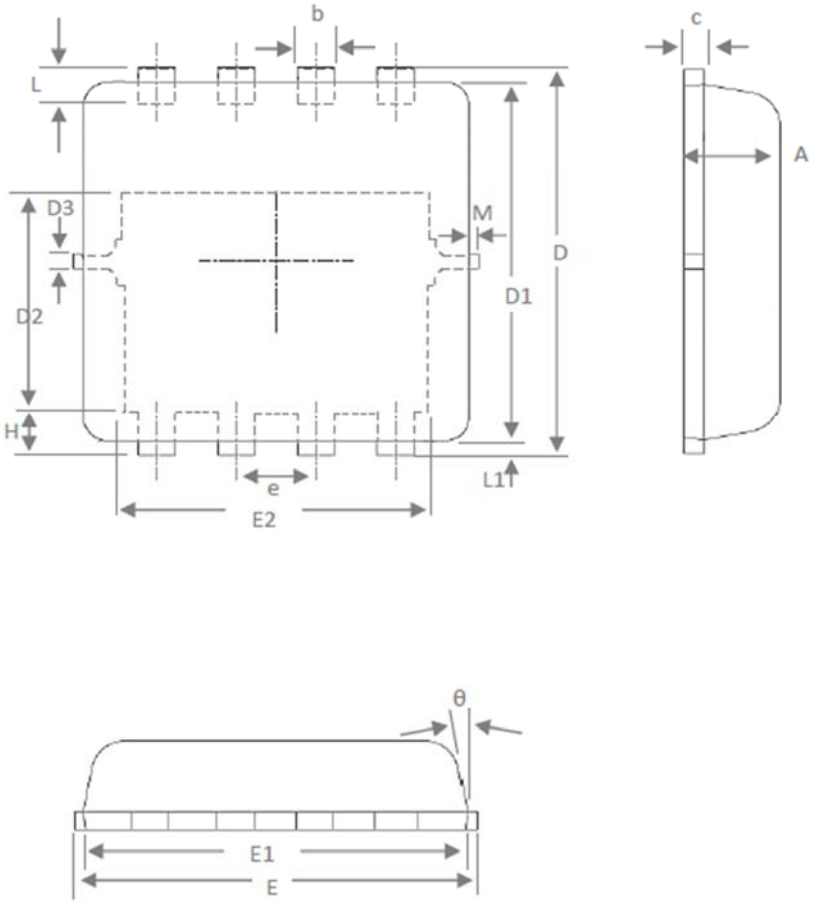
Marking Information

PDFN 3.3x3.3-8L (E)	Marking Rule
Laser Marking  	Line 1：Device Name P3008E Line 2：Date Code YMMXXX Y：Year Code MM：Month Code XXX：Serial Number Year Code Description As Below

Year Code Description

Year Code	Year	
0	2010	2020
1	2011	2021
2	2012	2022
3	2013	2023
4	2014	2024
5	2015	2025
6	2016	2026
7	2017	2027
8	2018	2028
9	2019	2029

Package of Dimension

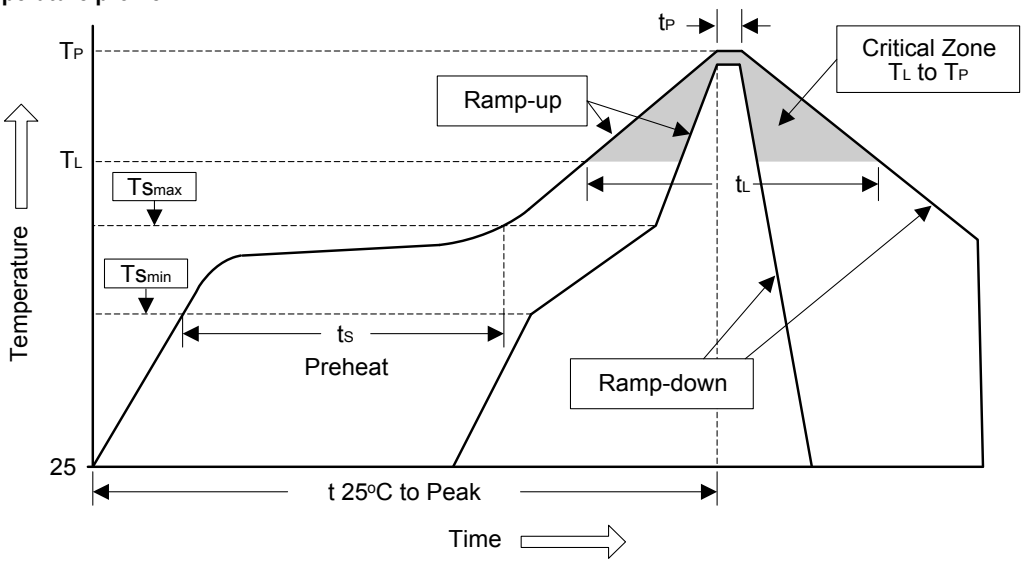


Symbol	Min	Nor	Max
A	0.70	0.75	0.80
b	0.25	0.30	0.35
c	0.10	0.15	0.25
D	3.25	3.35	3.45
D1	3.00	3.10	3.20
D2	1.78	1.88	1.98
D3	-	0.13	-
E	3.00	3.30	3.40
E1	3.00	3.15	3.20
E2	2.39	2.49	2.59
e		0.65BSC	
H	0.30	0.39	0.50
L	0.30	0.40	0.50
L1	-	0.13	-
θ	-	10°	12°
M	-	-	0.15

Soldering Methods for Silicongear's Products

1. Storage environment: Temperature=10°C to 35°C Humidity=65%±15%
2. Reflow soldering of surface-mount devices

Figure 1: Temperature profile



Profile Feature	Sn-Pb Eutectic Assembly	Pb-Free Assembly
Average ramp-up rate (T_L to T_P)	<3°C/sec	<3°C/sec
Preheat - Temperature Min (Ts_{min}) - Temperature Max (Ts_{max}) - Time (min to max) (ts)	 100°C 150°C 60 to 120 sec	 150°C 200°C 60 to 180 sec
Tsmax to T_L - Ramp-up Rate	 <3°C/sec	 <3°C/sec
Time maintained above: - Temperature (T_L) - Time (t_L)	 183°C 60 to 150 sec	 217°C 60 to 150 sec
Peak Temperature (T_P)	240°C +0/-5°C	260°C +0/-5°C
Time within 5°C of actual Peak Temperature (t_P)	10 to 30 sec	20 to 40 sec
Ramp-down Rate	<6°C/sec	<6°C/sec
Time 25°C to Peak Temperature	<6 minutes	<8 minutes

3. Flow (wave) soldering (solder dipping)

Products	Peak Temperature	Dipping Time
Pb devices.	245°C ±5°C	5sec ±1sec
Pb-Free devices.	260°C +0/-5°C	5sec ±1sec

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